Contents

Nomenclature xi

1 Introduction 1
- 1.1 Packaging of semiconductor power modules . . . 2
- 1.2 Bond-position-depending joining conditions and challenges . . . 5
- 1.3 Classification of wire bonding into joining technologies . . . 6
  - 1.3.1 Commonly-used cold welding processes . . . 6
  - 1.3.2 Ultrasonic based joining technologies . . . 7
- 1.4 Contribution of this thesis . . . 9

2 State of scientific knowledge of wire bonding processes 11
- 2.1 Functioning of ultrasonic wire bonding . . . 11
  - 2.1.1 Vibration system of ultrasonic wire bond machines . . . 13
  - 2.1.2 Functionality and materials of wire bonding tools . . . 18
  - 2.1.3 Ultrasonic softening effect . . . 21
  - 2.1.4 Material characteristics of copper wires and copper substrates . . . 25
  - 2.1.5 Determination of joining quality . . . 27
- 2.2 Friction modeling of solid bodies . . . 31
  - 2.2.1 Surface friction modeling . . . 31
  - 2.2.2 Abrasion modeling . . . 35
- 2.3 Contributing factors for cold weld processes . . . 36
  - 2.3.1 Contaminant and oxide layers . . . 36
  - 2.3.2 Plastic deformation and surface approaching . . . 38
- 2.4 Modeling approaches for different cold weld processes . . . 38
  - 2.4.1 Modeling of the ball/wedge wire bonding process . . . 40
  - 2.4.2 Modeling of the wedge/wedge wire bonding process . . . 42

3 Friction approach for modeling the joining process 47
- 3.1 Estimating the ultrasonic softening effect . . . 58
- 3.2 Modeling the pre-deformation of wire and substrate . . . 59
- 3.3 Elasto-plastic deformation during wire bonding . . . 62
- 3.4 Predicting the normal pressure distribution in the contact areas . . . 64
  - 3.4.1 Influence of the tool excitation on the pressure distributions . . . 66
  - 3.4.2 Influence of the adhesion on the pressure distributions . . . 67
  - 3.4.3 Influence of the tool geometry on the normal pressure distribution 68
- 3.5 Modeling the clamping of tool and wire . . . 72
  - 3.5.1 Modeling approach to determine tangential force transmission characteristics of bond tools . . . 75
  - 3.5.2 Tool-shape-dependent transmittable tangential forces . . . 77

Bibliografische Informationen
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3.5.3 Implementation of tangential-force displacement curves into analytical model 80
3.6 Modeling the friction between wire and substrate 80
3.6.1 Determination of contact stiffness between wire and substrate . . 82
3.6.2 Masing model 84
3.6.3 Coupled point contact element simulation 86
3.7 Metallic joint forming model for predicting micro welds 97
3.8 Predicting the bonding quality and the shear force value 102
3.9 Experimental validation of the wire bond model 107
3.10 Summary and comparison of the friction model approach to published models 115

4 Substrate deformation and substrate vibration induced disturbances 117
4.1 Influence of static mechanical deformation on the bond quality 118
4.1.1 Mechanical fixation of molded connector pads in power semiconductor modules 118
4.1.2 Measuring and modeling of the quasi-static mechanical deformation of power semiconductor modules 121
4.1.3 Influence determination of tilting angle on the bond quality 122
4.2 Influence of substrate vibrations on the bond quality 131
4.3 Influences of power module vibrations on the bond quality 138
4.3.1 Influence of clamping device on the mechanical bond position properties 141
4.3.2 Measuring and modeling of module vibrations 144
4.3.3 Model to predict substrate vibration influences on the bond quality 150

5 Summary and Conclusions 157

Bibliography 161